



## MEP2326W3XL09-H5

### Multi-Wavelength SMD Type

#### Features

- Small 6-Pin package
- Multi-wavelength  
Peak wavelength:  
SIR=880nm, R=660nm  
Dominant wavelength:  
G=525nm
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

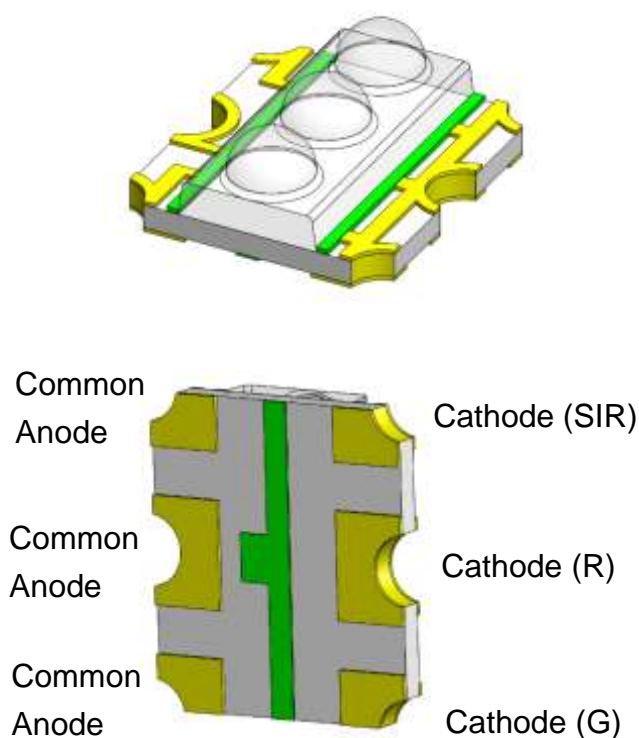
#### Applications

- Infrared sensor
- Oximeter

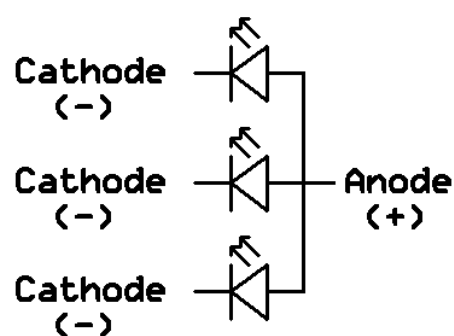
#### Description

The MEP2326W3XL09-H5 is multiple LED housed in a miniature SMD package. The device has many peak wavelength LED spectrally matched with phototransistor or photodiode.

#### Package Outline



#### Schematic





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### Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
I <sub>F</sub>	Continuous Forward Current	SIR <sub>(880)</sub>	70	mA	
		G <sub>(525)</sub>	20		
		R <sub>(660)</sub>	50		
I <sub>FP</sub>	Peak Forward Current	SIR <sub>(880)</sub>	0.7	A	1
		G <sub>(525)</sub>	0.1		
		R <sub>(660)</sub>	0.3		
V <sub>R</sub>	Reverse Voltage		5	V	
T <sub>opr</sub>	Operating Temperature		-40 ~ +85	°C	
T <sub>stg</sub>	Storage Temperature		-40 ~ +100	°C	
T <sub>sol</sub>	Soldering Temperature		260	°C	2
P <sub>D</sub>	Power Dissipation at(or below) 25°C Free Air Temperature	SIR <sub>(880)</sub>	140	mW	
		G <sub>(525)</sub>	68		
		R <sub>(660)</sub>	140		



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### Electro-Optical Characteristics $T_A = 25^\circ\text{C}$ (unless otherwise specified)

#### Optical Characteristics (SIR<sub>(880)</sub>)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I <sub>e</sub>	Radiant Intensity	I <sub>F</sub> =20mA	4.0	-	7.4	mW/sr	
		I <sub>F</sub> =70mA	-	19	-		
λ <sub>p</sub>	Peak Wavelength	I <sub>F</sub> =20mA	870	880	890	nm	
Δλ	Spectral Bandwidth	I <sub>F</sub> =20mA	-	30	-	nm	
θ <sub>1/2</sub>	Angle of Half Intensity	I <sub>F</sub> =20mA	-	±37.5	-	deg	

#### Electrical Characteristics (SIR<sub>(880)</sub>)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =20mA	1.20	1.35	1.7	V	
		I <sub>F</sub> =70mA	1.30	1.47	2.0		
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	10	μA	

#### Optical Characteristics (G<sub>(525)</sub>)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I <sub>v</sub>	Luminous Intensity	I <sub>F</sub> =20mA	2800	-	5200	mcd	
I <sub>e</sub>	Radiant Intensity	I <sub>F</sub> =20mA	5.0	7.8	11.0	mW/sr	
P <sub>o</sub>	Total Radiated Power	I <sub>F</sub> =20mA	-	10	-	mW	
λ <sub>p</sub>	Peak Wavelength	I <sub>F</sub> =20mA	-	520	-	nm	
λ <sub>d</sub>	Dominant Wavelength	I <sub>F</sub> =20mA	515	525	535	nm	
Δλ	Spectral Bandwidth	I <sub>F</sub> =20mA	-	30	-	nm	
θ <sub>1/2</sub>	Angle of Half Intensity	I <sub>F</sub> =20mA	-	±37.5	-	deg	

#### Electrical Characteristics (G<sub>(525)</sub>)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =20mA	1.9	2.75	3.3	V	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	10	μA	



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#### Optical Characteristics ( $R_{(660)}$ )

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I <sub>e</sub>	Radiant Intensity	I <sub>F</sub> =20mA	6	-	14	mW/sr	
		I <sub>F</sub> =50mA	-	20	-		
λ <sub>p</sub>	Peak Wavelength	I <sub>F</sub> =20mA	655	660	665	nm	
Δλ	Spectral Bandwidth	I <sub>F</sub> =20mA	-	20	-	nm	
θ <sub>1/2</sub>	Angle of Half Intensity	I <sub>F</sub> =20mA	-	±37.5	-	deg	

#### Electrical Characteristics ( $R_{(660)}$ )

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =20mA	1.6	2.0	2.4	V	
		I <sub>F</sub> =50mA	1.9	2.3	2.8		
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	10	μA	

#### Notes:

1. I<sub>FP</sub> Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%.
2. Soldering time ≤ 5 seconds.



## Typical Characteristic Curves

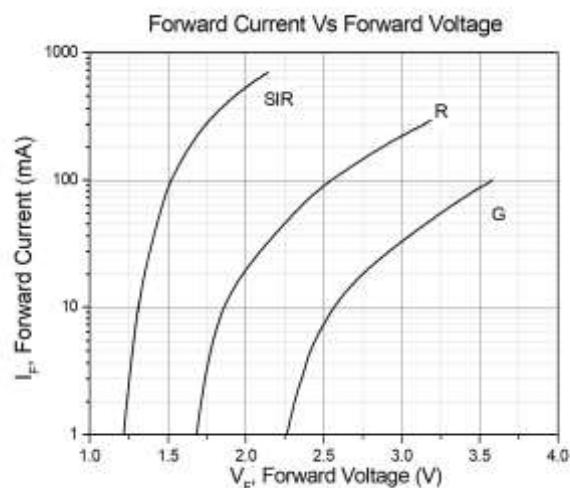


Figure 1

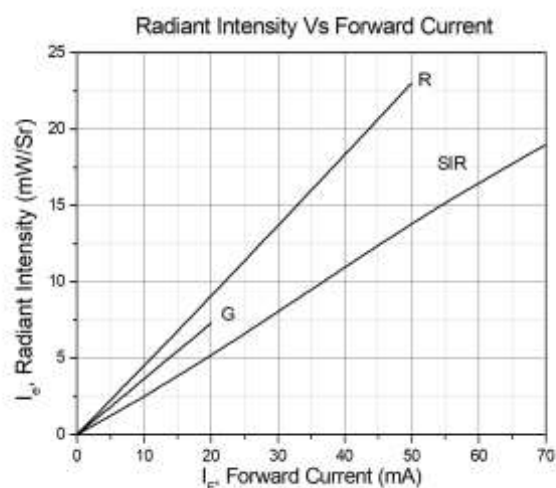


Figure 2

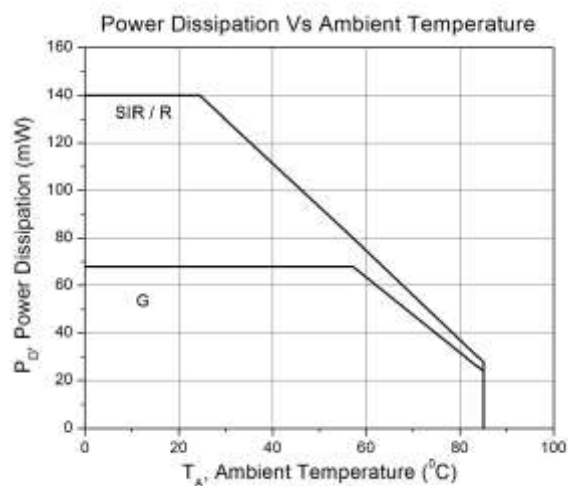


Figure 3

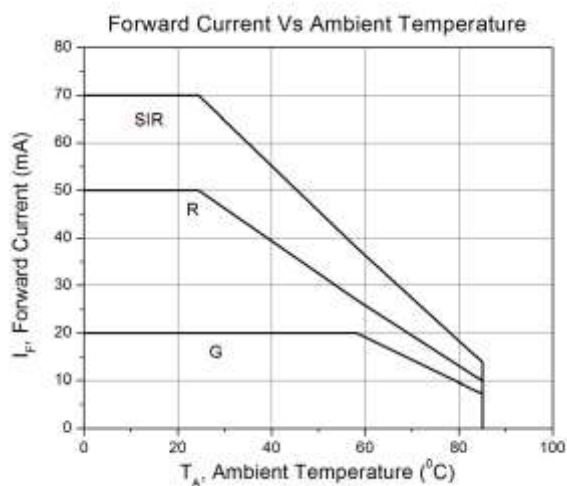


Figure 4

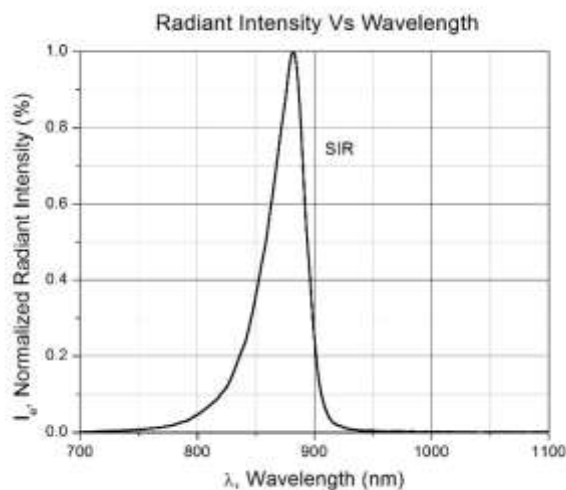


Figure 5

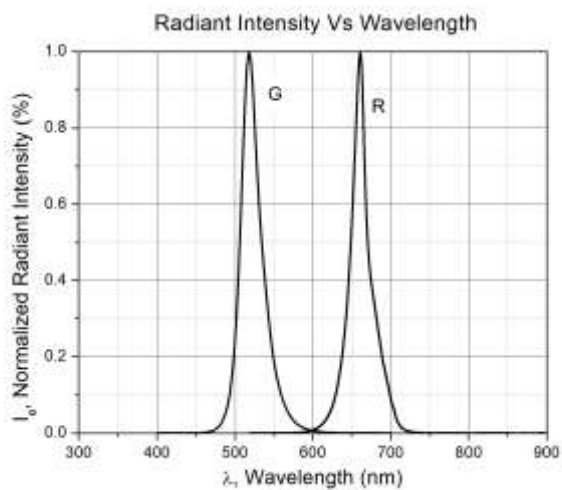
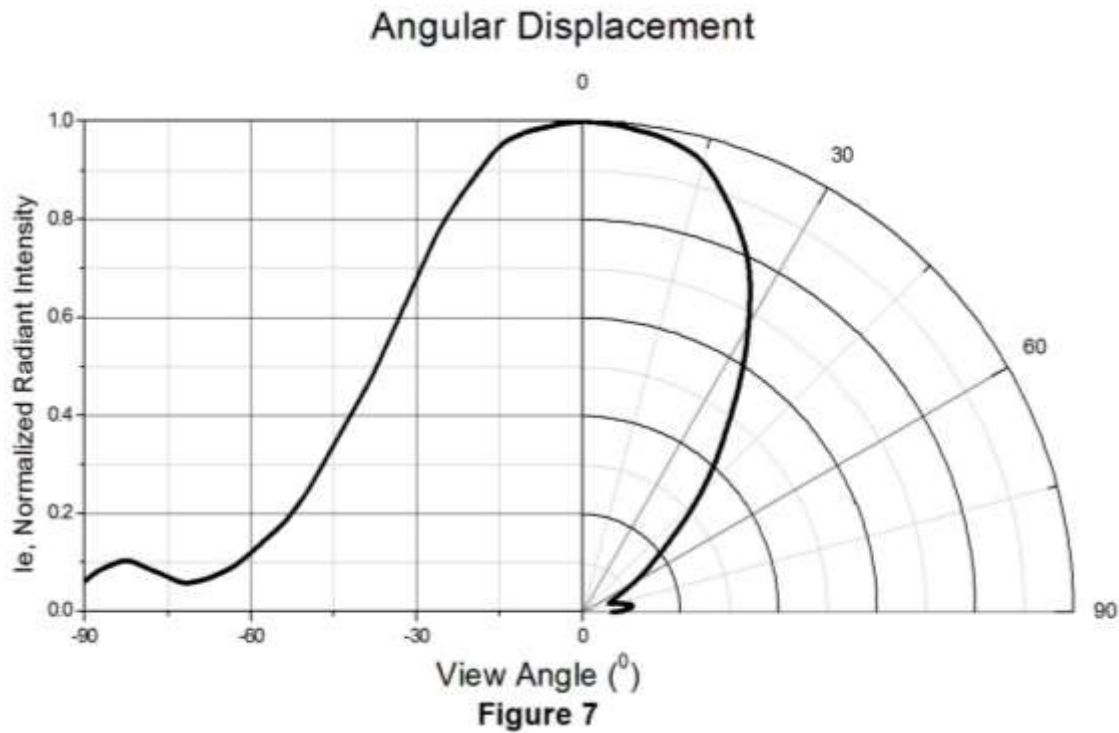


Figure 6



Typical Characteristic Curves

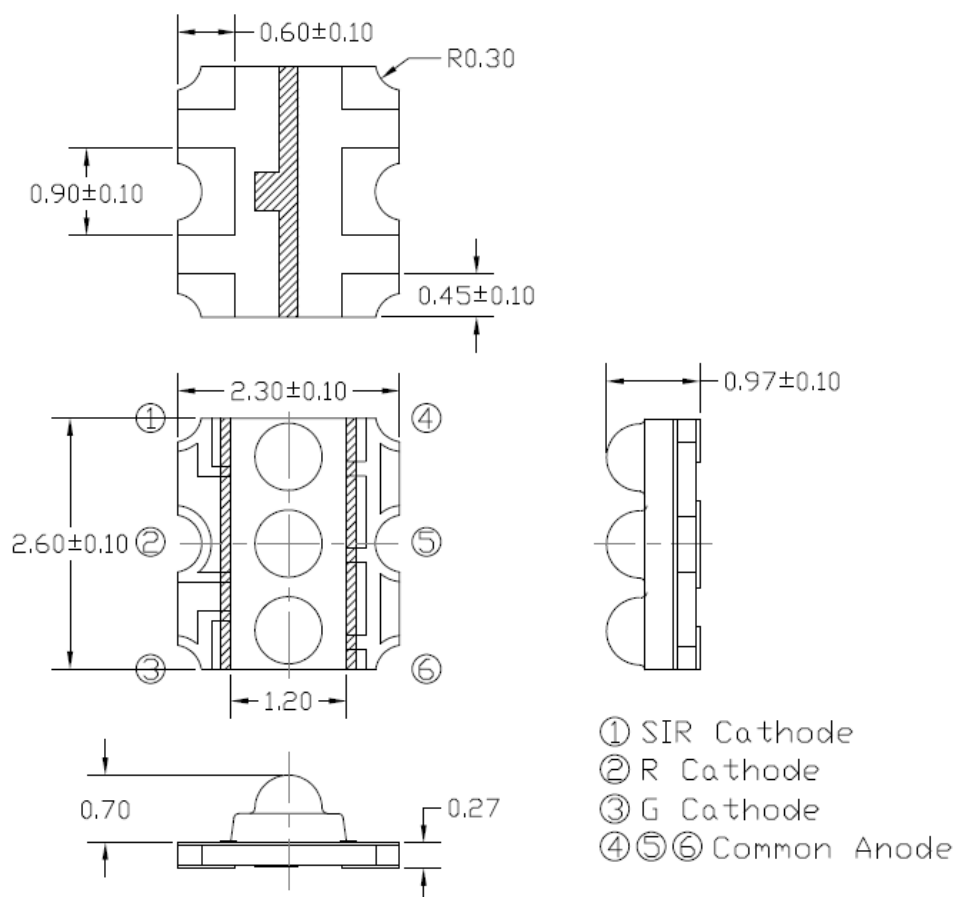




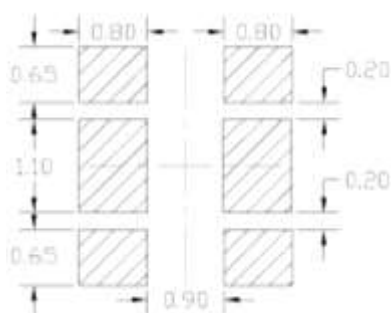
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Multi-Wavelength SMD Type

## Package Dimension *All dimensions are in mm, unless otherwise stated*



## Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*

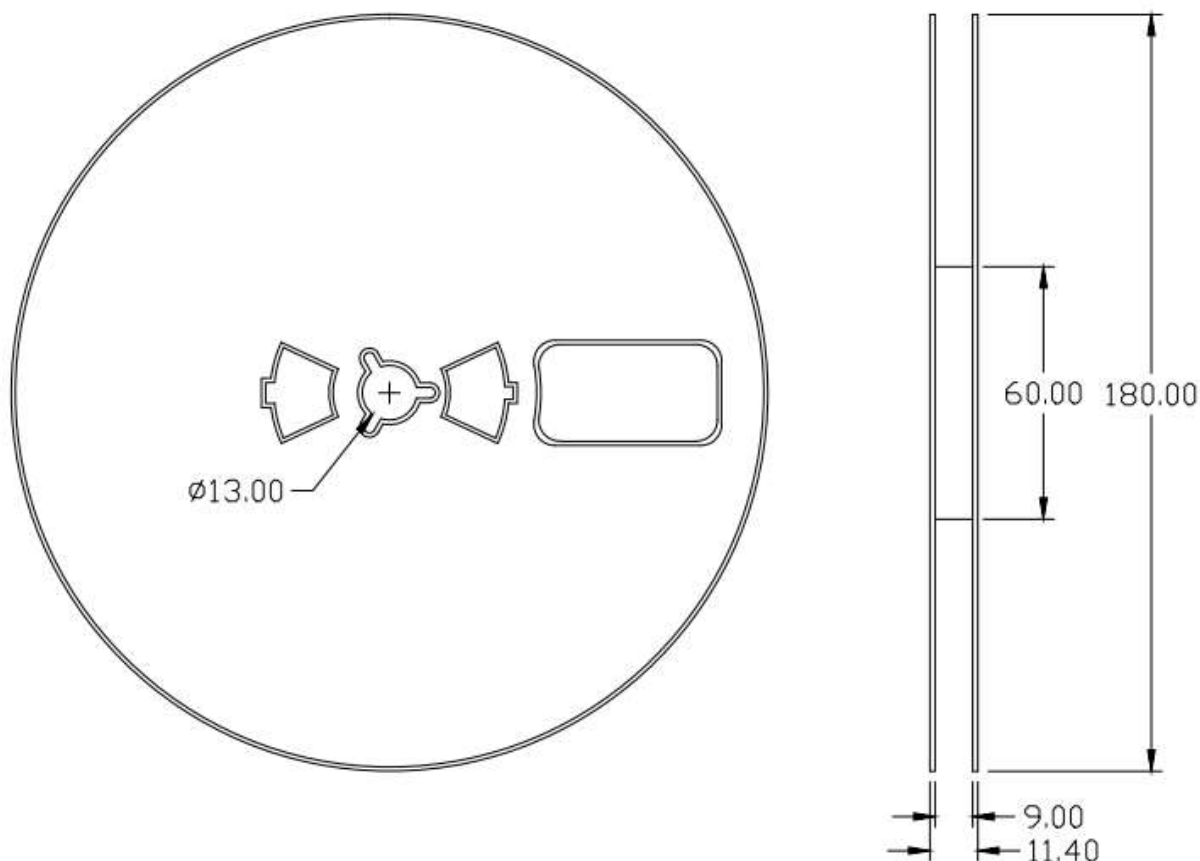


## Ordering Information

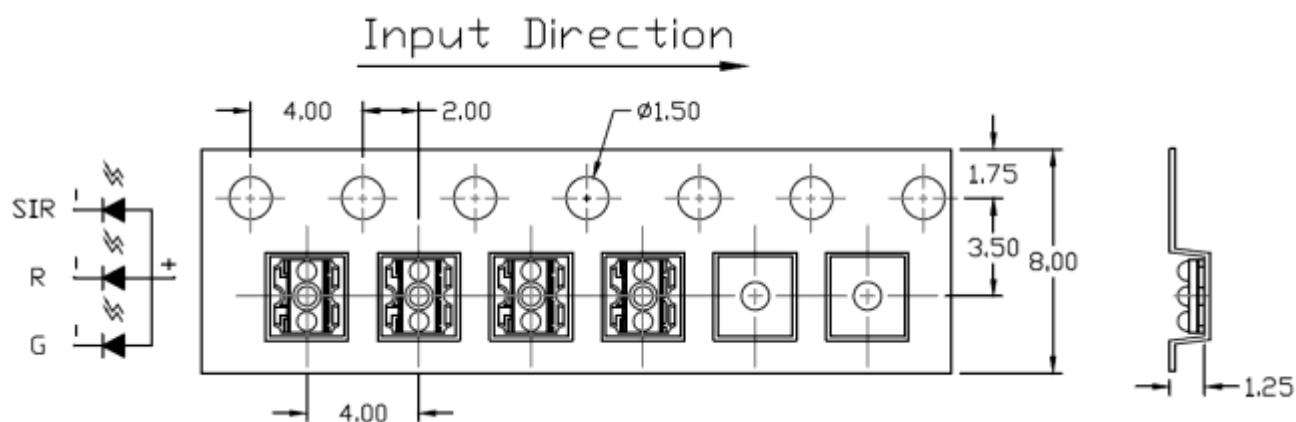
Part Number	Description	Quantity
MEP2326W3XL09-H5	Tape & Reel	4000 pcs



**Reel Dimension** *All dimensions are in mm, unless otherwise stated*



**Tape Dimension** *All dimensions are in mm, unless otherwise stated*



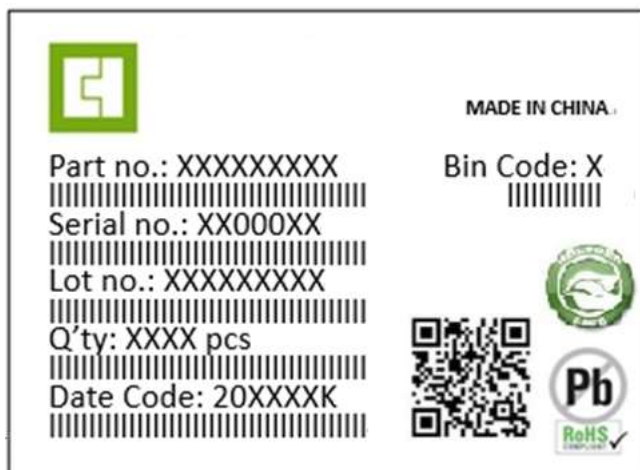




## MEP2326W3XL09-H5

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#### Label Form Specification



Part no: CTM Production Number  
Serial no: Production Number  
Lot no: Lot number  
Q'ty: Packing Quantity  
Date Code: Manufacture Date  
Bin Code: 1e Ranks  
MADE IN CHINA: Production Place

#### Storage Condition

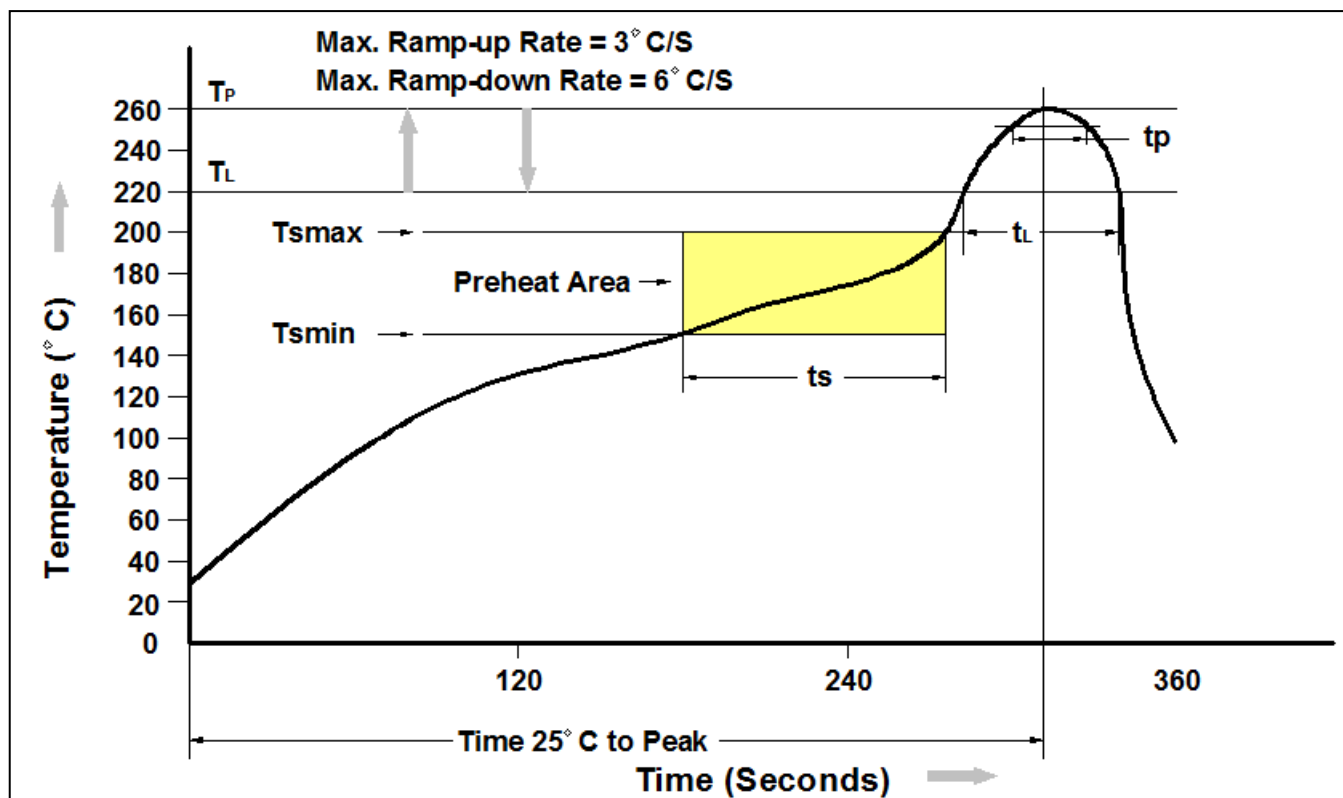
1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.  
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



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### Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. ( $T_{smin}$ )	150°C
Temperature Max. ( $T_{smax}$ )	200°C
Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60-120 seconds
Ramp-up Rate ( $t_L$ to $t_P$ )	3°C/second max.
Liquidous Temperature ( $T_L$ )	217°C
Time ( $t_L$ ) Maintained Above ( $T_L$ )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time ( $t_P$ ) within 5°C of 260°C	30 seconds
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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